



1. Bolt down on heatsink with silicon thermal compound between bridge and mounting surface for maximum heat transfer
2. Unit mounted on 4.0" x 4.0" x 0.11" (10.5cm x 10.5cm x 0.3cm) AL plate
3. Unit mounted on PCB at 0.375" (9.5mm) lead with 0.5" x 0.5" (12mm x 12mm) copper pads



RATINGS AND CHARACTERISTIC CURVES GBPC6005 THRU GBPC610

